

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L18	164	257/737,738,747,778,783,789,793,795.ccls. and (passive near device or smd or resistor or capacitor or passive near smd or passive near smt) near6 (solder\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:44
L15	9	257/737,738,747,778,783,789,793,795.ccls. and (passive near device or smd or resistor or capacitor or passive near smd or passive near smt) near10 (underfill\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:43
L17	121	257/737,738,747,778,783,789,793,795.ccls. and (two near terminal or two-terminal or dogbone or dog-bone)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:35
L16	3	257/737,738,747,778,783,789,793,795.ccls. and (passive near device or smd or resistor or capacitor or passive near smd or passive near smt) near5 (two near terminal or two-terminal or dogbone or dog-bone)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 12:34
L14	1243	257/737,738,747,778,783,789,793,795.ccls. and (passive near device or smd or resistor or capacitor or passive near smd or passive near smt)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:39
L13	312	257/795.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:38
L12	469	257/793.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 11:22
L10	438	257/789.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 10:51
L11	14	(encapsulant or encapsulation) near5 (resin) near2 (flux\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 10:25

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L9	14	(encapsulant or encapsulation) near5 (epoxy) near2 (flux\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 10:25
L8	17	underfill\$4 near8 (encapsulant or encapsulation) near8 (epoxy) near5 (flux\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 10:22
L7	271	257/747.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 10:10
L6	3	(underfill\$4) near15 (one near part near2 epoxy) near8 (flux\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 09:45
L4	10	(surface near mount\$2 or chip or mounted or mounting or decoupling or smt or smd) near2 (capacitor or resistor or diode or inductor) and (chip or die or ic) near4 (underfill\$3 or under-fill\$3) and (resin near5 epoxy near5 (flux\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 09:45
S58	262	(surface near mount\$2 or chip or mounted or mounting or decoupling or smt or smd) near2 (capacitor or resistor or diode or inductor) and (chip or die or ic) near4 (underfill\$3 or under-fill\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 09:41
L3	17	("5311405").URPN.	USPAT	OR	ON	2006/03/27 09:35
L2	8	("5311405" "6150193" "6177731" "6228466" "6245594" "6294840" "6388335" "6448644").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/27 09:34
L1	2	"6521997".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/27 09:34
S61	29	"5399903".pn. "5969461".pn. "6614122".pn. "6338985".pn. "6663943".pn. "6693239".pn. "6107679".pn. "5459368".pn. "5900581".pn. "5720100".pn. "6560120".pn. "5969461".pn. "6586007".pn. "6899544".pn. "6521997".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 13:41

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S60	91	((two-terminal or two adj terminal or dogbone) near2 (capacitor or resistor or device or smd or smt or surface near mount or flip near chip)) same (solder\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 13:39
S59	57	((two-terminal or two adj terminal or dogbone or passive) near2 (capacitor or resistor or device or smd or smt or surface near mount)) same (underfill\$4 or under-fill\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 13:34
S57	19	(US-20020035201-\$ or US-20030080437-\$ or US-20020131253-\$ or US-20040040740-\$ or US-20030171456-\$ or US-20030170450-\$ or US-20010023983-\$ or US-20020062970-\$ or US-20030075805-\$).did. or (US-6555414-\$ or US-6409070-\$ or US-6018192-\$ or US-6459561-\$ or US-6440777-\$ or US-5529957-\$ or US-5493259-\$ or US-6011683-\$ or US-6399178-\$ or US-6727119-\$).did.	US-PGPUB; USPAT	OR	ON	2006/03/24 13:02
S56	4	"20030170450" "6409070".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 13:02
S55	16	"4339785".pn. "5085364".pn. "5493259".pn. "5529957".pn. "5814401".pn. "6071371".pn. "6202917".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 13:02
S54	12	"6489180".pn. "20030080437" "6458472".pn. "6238223".pn. "5128746".pn. "5579573".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 12:58
S53	398	(chip or die) adj capacitor same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 12:56

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S51	120	capacitor near3 (bonded or mounted or mounting or mount or adhered or bonding or adhering or affixed or affixing) near3 (pwb or pcb or circuit adj board or wiring adj board or package near substrate or carrier near substrate or interposer or substrate) same (encapsula\$6 or molding or underfill\$3 or epoxy or resin or resinous) same (solder or soldering or soldered)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/24 12:28
S50	54	surface near mount near capacitor same (encapsulant or encapsulation or encapsulating or resin or epoxy or underfill or underfilling or under-fill or molding or adhesive)	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/24 11:15
S49	199	(passive near3 device or smd or resistor or capacitor or diode) near10 (noflow or no-flow or reflow or preform or preformed or strip) near3 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy or polymer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 11:05
S48	17	(passive near3 device or smd or resistor or capacitor or diode) near6 (bonded or flip adj chip or mounted or mount) near10 (noflow or no-flow or reflow or preform or preformed) near6 (resin or underfill or under-fill or underfilling or encapsulant or encapsulation or encapsulate or encapsulating or mold or molding or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/24 11:01